

Special Issue

Microwave Passive Components

Message from the Guest Editor

Nowadays, devices and systems based on micro-, millimeter and terahertz waves are widely used in all aspects of life. Microwave passive components play an important role. The development of advanced machining technologies such as the Micro-Electro-Mechanical System (MEMS), 3D-printing, and micro-/nanomachining, machining accuracy and ability of passive components, especially, have been improved greatly. In addition, novel concepts and mechanisms have been continually introduced or proposed from other fields, including meta-material, vortex electromagnetic wave and spoof surface plasmon. As a result, microwave passive devices/components have entered a new stage controlled by information coding, and may contribute to the miniaturization and integration of RF circuits and devices. Therefore, this Special Issue, named “Microwave Passive Components”, was born. This Special Issue will accept research papers and review articles focusing on the theory, modeling, simulation, measurement and applications of passive components, circuits, devices and systems in the microwave, millimeter-wave and terahertz-wave bands.

Guest Editor

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